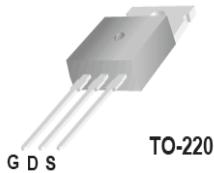


# TSP70R210S1

## 700V 20A N-Channel SJ-MOSFET

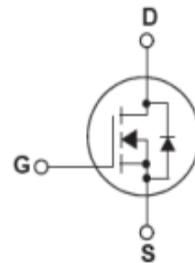
### General Description

Truesemi SJ-FET is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance. This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. SJ-FET is suitable for various AC/DC power conversion in switching mode operation for higher efficiency.



### Features

- 750V @ $T_J = 150\text{ }^{\circ}\text{C}$
- Typ.  $R_{DS(on)} = 0.19\Omega$
- Ultra Low gate charge (typ.  $Q_g = 70\text{nC}$ )
- 100% avalanche tested



### Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
$V_{DSS}$	Drain-Source Voltage	700	V
$I_D$	Drain Current -Continuous ( $TC = 25\text{ }^{\circ}\text{C}$ )	20	A
	-Continuous ( $TC = 100\text{ }^{\circ}\text{C}$ )	12.6	
$I_{DM}$	Drain Current – Pulsed (Note 1)	62	A
$V_{GSS}$	Gate-Source voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	485	mJ
$I_{AR}$	Avalanche Current (Note 1)	3.5	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	1	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ (Note 3)	15	V/ns
$P_D$	Power Dissipation ( $TC = 25\text{ }^{\circ}\text{C}$ )	151	W
	-Derate above $25\text{ }^{\circ}\text{C}$	1.67	$\text{W}/\text{ }^{\circ}\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$
$T_L$	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	$^{\circ}\text{C}$

\* Drain current limited by maximum junction temperature.

### Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.83	$^{\circ}\text{C}/\text{W}$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	$^{\circ}\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62	$^{\circ}\text{C}/\text{W}$

## Electrical Characteristics TC = 25°C unless otherwise noted

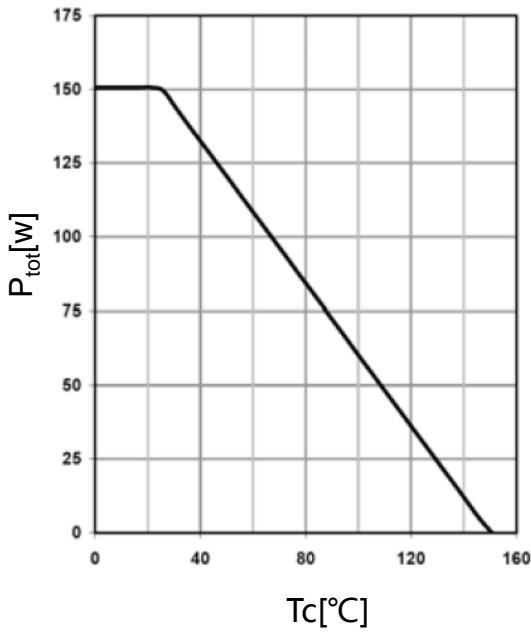
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Off Characteristics						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A, T_J = 25^\circ C$	700	--	--	V
		$V_{GS} = 0V, I_D = 250\mu A, T_J = 150^\circ C$	--	750	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu A$ , Referenced to $25^\circ C$	--	0.6	--	V/°C
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 700V, V_{GS} = 0V, -T_J = 150^\circ C$	--	-- 10	1	$\mu A$ $\mu A$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 30V, V_{DS} = 0V$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -30V, V_{DS} = 0V$	--	--	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.5	--	4.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 10A$	--	0.19	0.21	$\Omega$
$g_{FS}$	Forward Trans conductance	$V_{DS} = 40V, I_D = 10A$ (Note 4)	--	16	--	S
Dynamic Characteristics						
$C_{iss}$	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$	--	1440	--	pF
$C_{oss}$	Output Capacitance		--	370	--	pF
$C_{rss}$	Reverse Transfer Capacitance		--	11	--	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 400V, I_D = 10A$ $R_G = 20\Omega$ (Note 4, 5)	--	15	--	ns
$t_r$	Turn-On Rise Time		--	11	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	110	--	ns
$t_f$	Turn-Off Fall Time		--	9	--	ns
$Q_g$	Total Gate Charge	$V_{DS} = 480V, I_D = 10A$ $V_{GS} = 10V$ (Note 4, 5)	--	70	90	nC
$Q_{gs}$	Gate-Source Charge		--	7.8	--	nC
$Q_{gd}$	Gate-Drain Charge		--	9	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
$I_s$	Maximum Continuous Drain-Source Diode Forward Current	--	--	20	A	
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current	--	--	60	A	
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0V, I_F = 10A$	--	1	1.5	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0V, I_F = 10A$ $di_F/dt = 100A/\mu s$ (Note 4)	--	475	--	ns
$Q_{rr}$	Reverse Recovery Charge		--	5.8	--	$\mu C$
$I_{rrm}$	Peak reverse recovery Current		--	35	--	A

### NOTES:

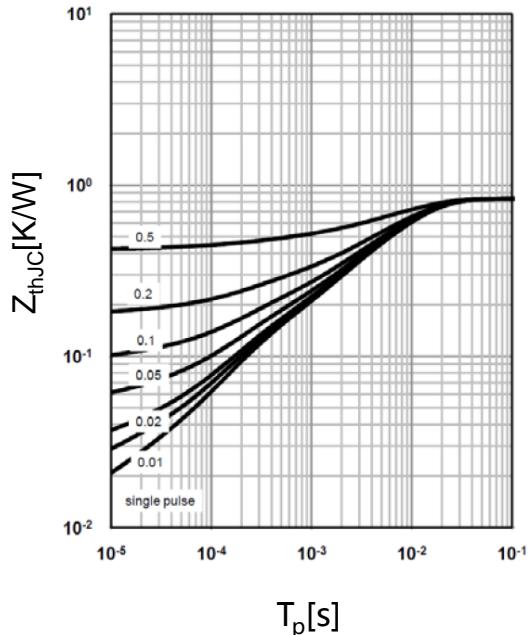
- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{AS} = 3.5A, V_{DD} = 50V$ , Starting  $T_J = 25^\circ C$
- $I_{SD} \leq 20A, di/dt \leq 200A/\mu s, V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ C$
- Pulse Test: Pulse width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$
- Essentially Independent of Operating Temperature Typical Characteristics

# Typical Performance Characteristics

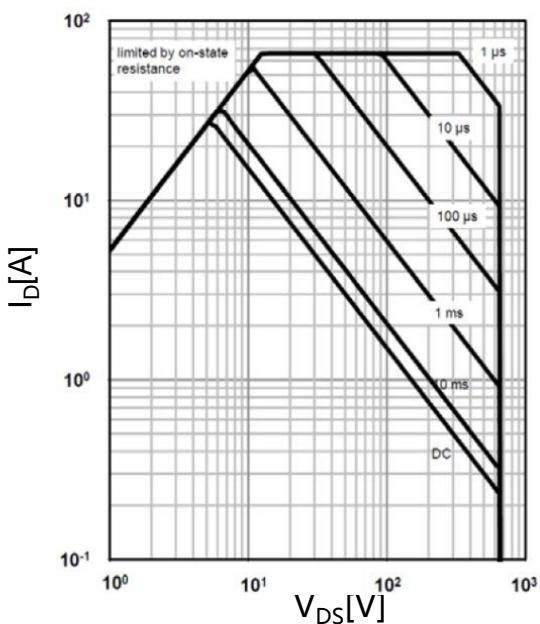
Power dissipation



Max. transient thermal impedance

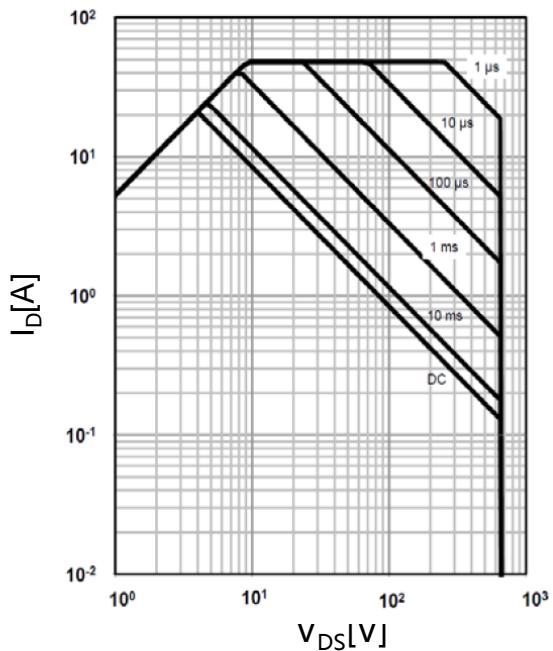


Safe operating area  $T_C=25$  °C



$I_D=f(V_{DS})$ ;  $T_C=25$  °C;  $V_{GS} > 7$  V;  
 $D=0$ ; parameter  $t_p$

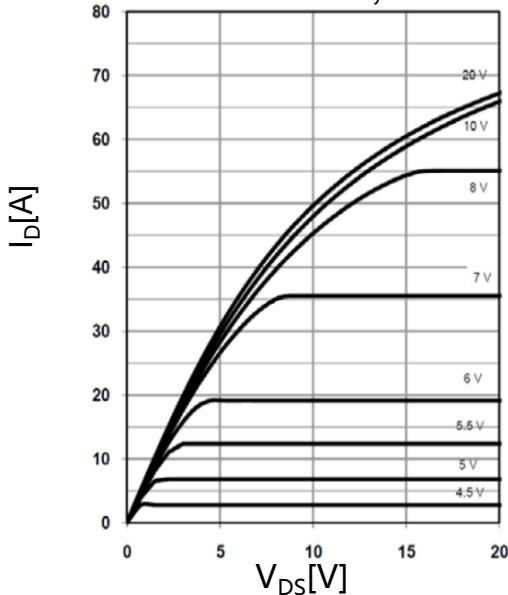
Safe operating area  $T_C=80$  °C



$I_D=f(V_{DS})$ ;  $T_C=80$  °C;  $V_{GS} > 7$  V;  
 $D=0$ ; parameter  $t_p$

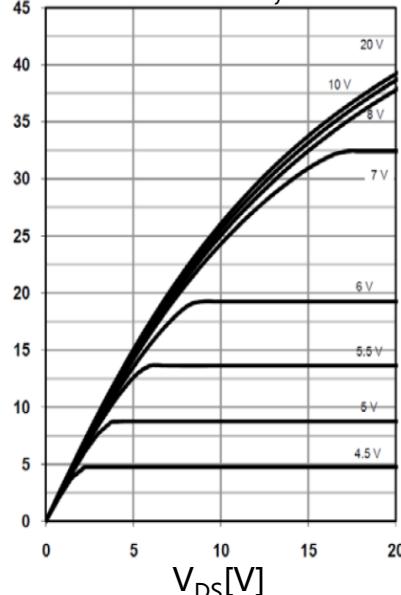
# Typical Performance Characteristics

Typ. output characteristics  $T_j=25\text{ }^\circ\text{C}$



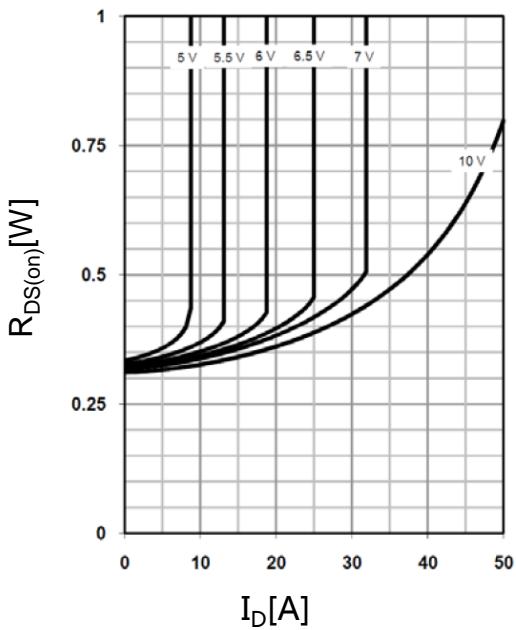
$I_D=f(V_{DS})$ ;  $T_j=25\text{ }^\circ\text{C}$ ; parameter:  $V_{GS}$

Typ. output characteristics  $T_j=125\text{ }^\circ\text{C}$



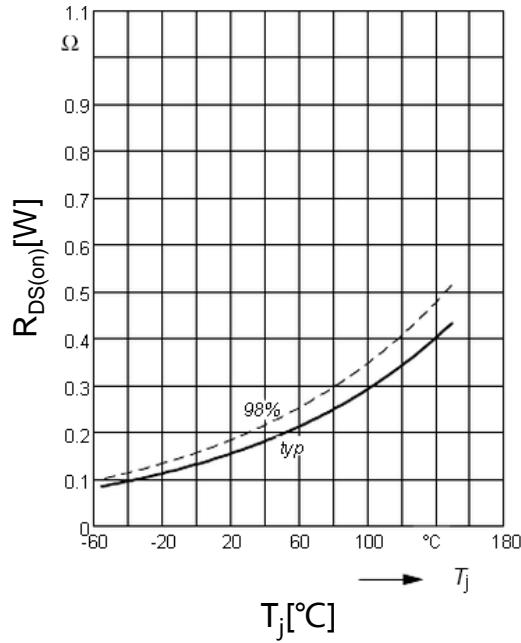
$I_D=f(V_{DS})$ ;  $T_j=125\text{ }^\circ\text{C}$ ; parameter:  $V_{GS}$

Typ. drain-source on-state resistance



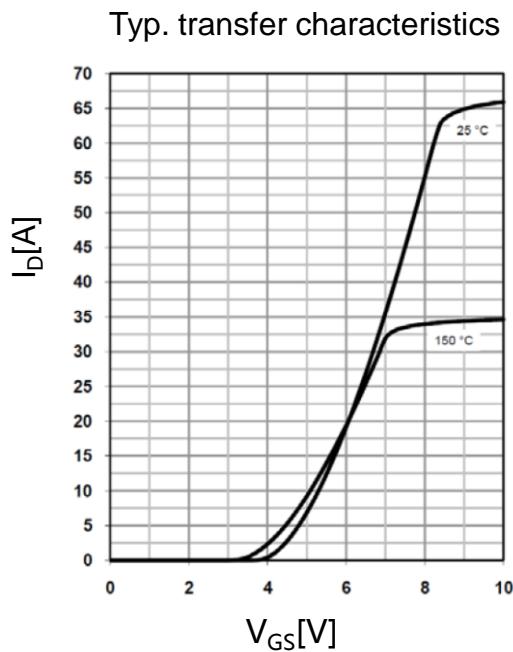
$R_{DS(on)}=f(I_D)$ ;  $T_j=125\text{ }^\circ\text{C}$ ;  
parameter:  $V_{GS}$

Typ. drain-source on-state resistance

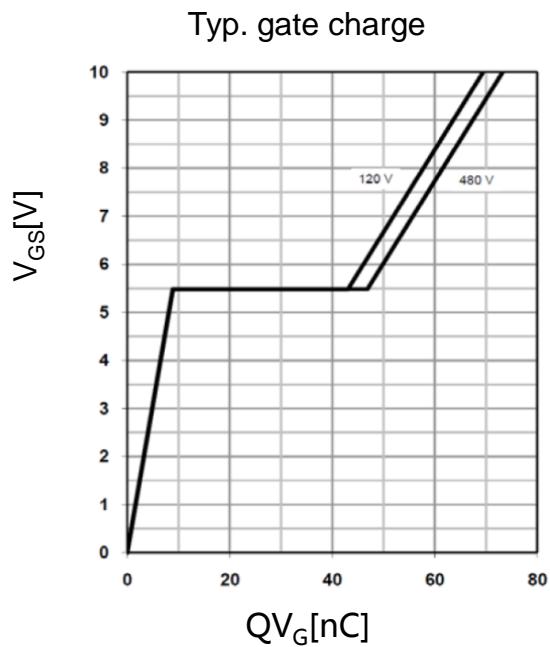


$R_{DS(on)}=f(T_j)$ ;  $I_D=7.3\text{ A}$ ;  $V_{GS}=10\text{ V}$

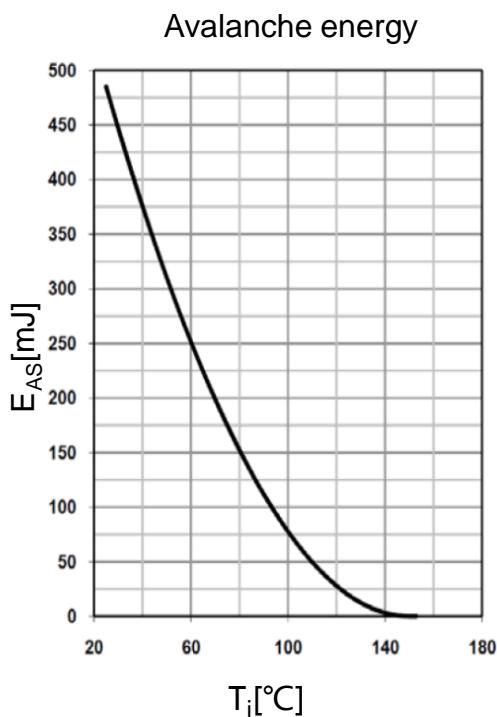
# Typical Performance Characteristics



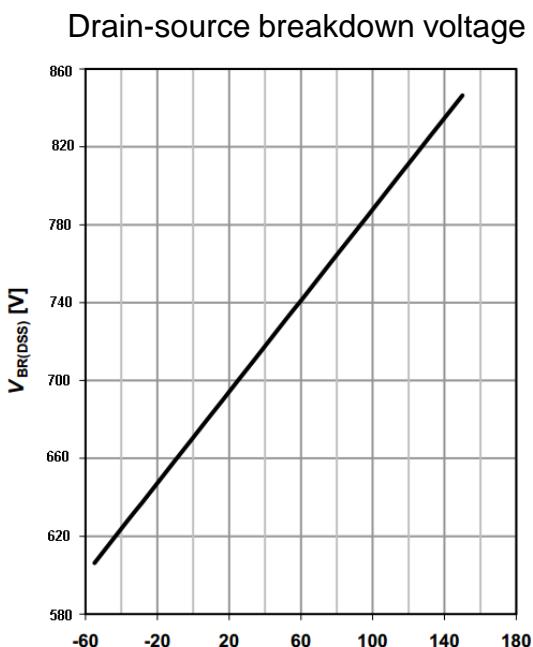
$$I_D = f(V_{GS}); V_{DS} = 20V$$



$$V_{GS} = f(Q_V); I_D = 11A \text{ pulsed}$$

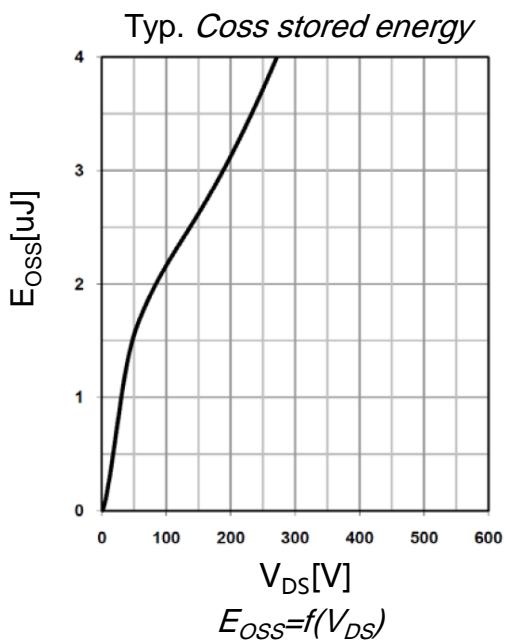
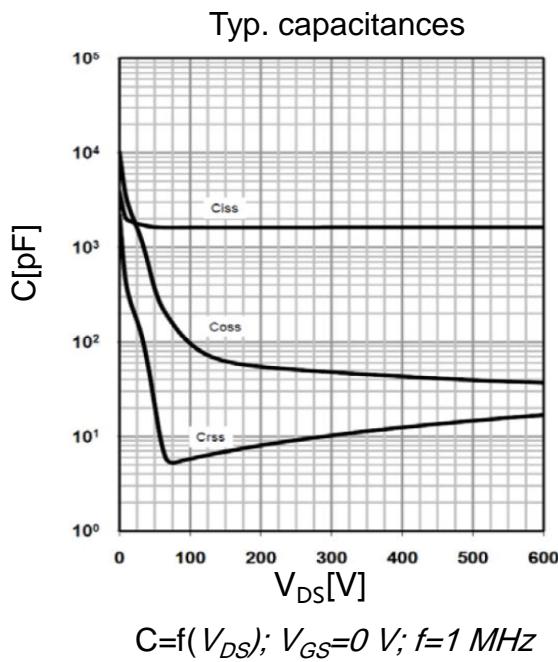


$$E_{AS} = f(T_j); I_D = 3.5A; V_{DD} = 50V$$

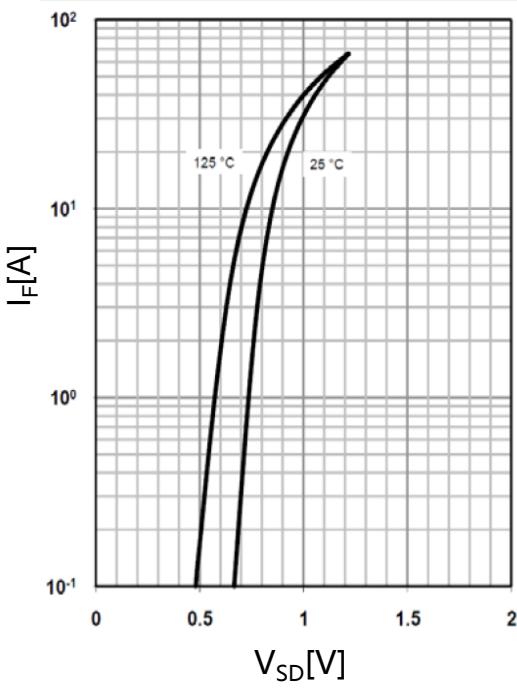


$$V_{BR(DSS)} = f(T_j); I_D = 1.0mA$$

# Typical Performance Characteristics



## Forward characteristics of reverse diode



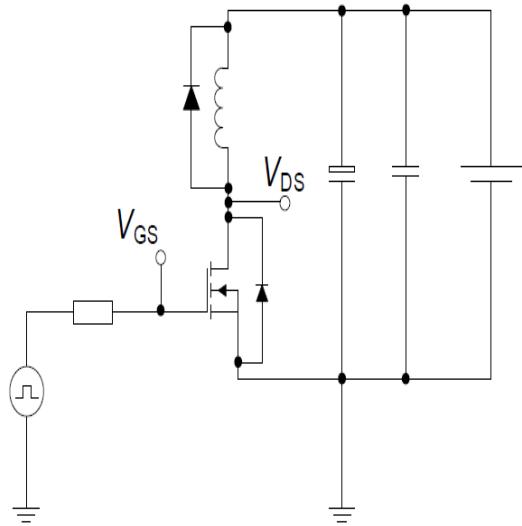
$I_F = f(V_{SD})$ ; parameter:  $T_j$

# Test circuits

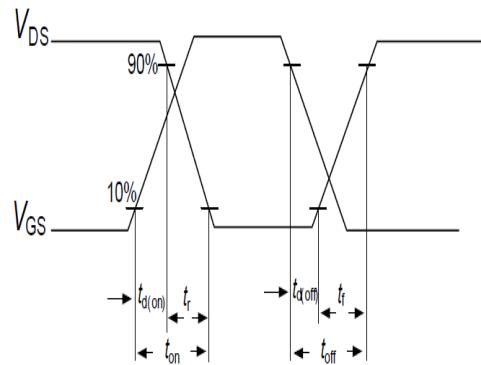
---

## Switching times test circuit and waveform for inductive load

Switching times test circuit for inductive load

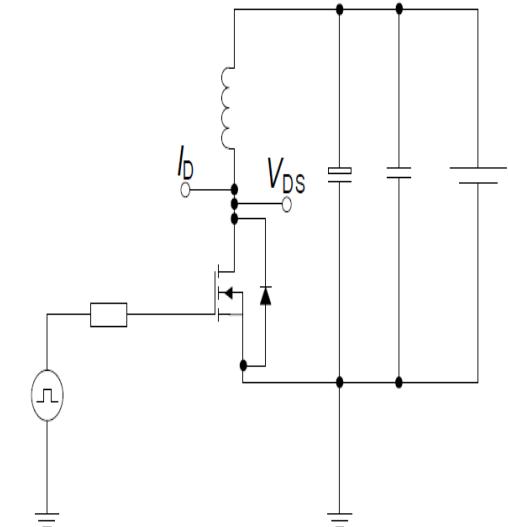


Switching time waveform

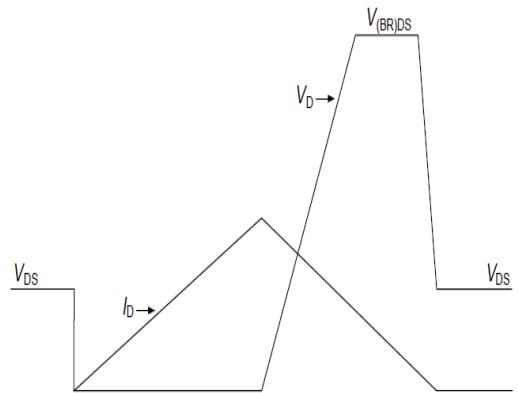


## Unclamped inductive load test circuit and waveform

Unclamped inductive load test circuit



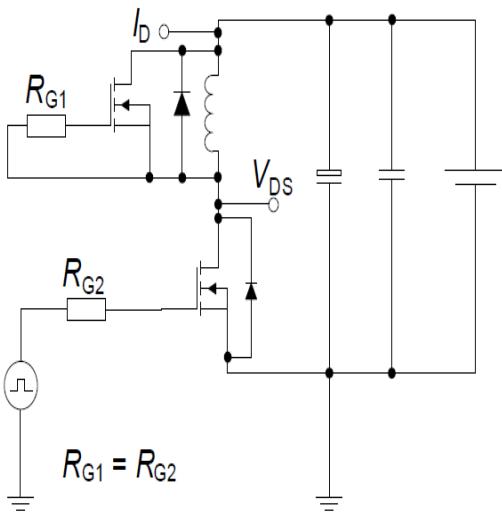
Unclamped inductive waveform



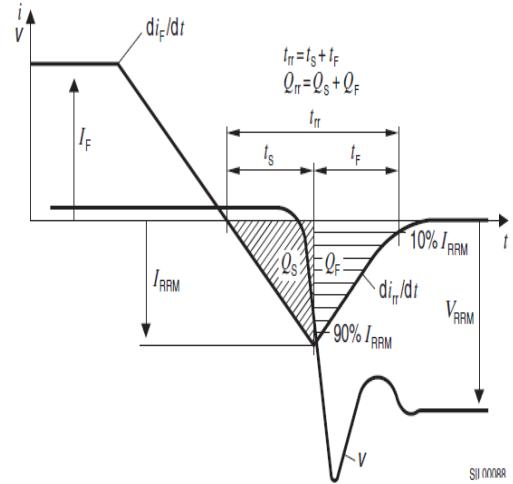
# Test circuits

## Test circuit and waveform for diode characteristics

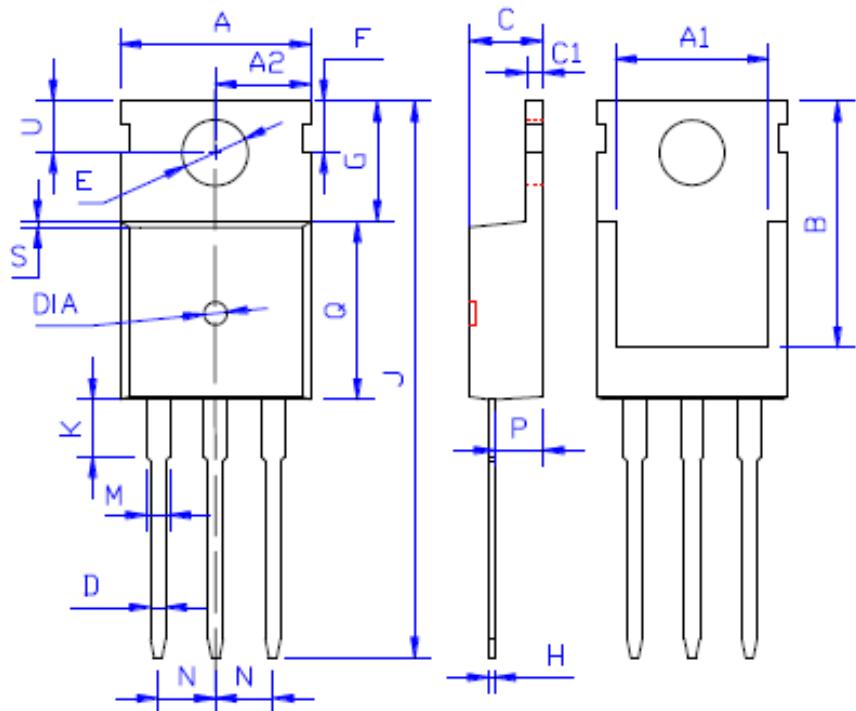
Test circuit for diode characteristics



Diode recovery waveform



# Package Outline TO-220



DIM	MILLIMETERS
A	10.00±0.30
A1	8.00±0.30
A2	5.00±0.30
B	13.20±0.40
C	4.50±0.20
C1	1.30±0.20
D	0.80±0.20
E	3.60±0.20
F	3.00±0.30
G	6.60±0.40
H	0.50±0.20
J	28.88±0.50
K	3.00±0.30
M	1.30±0.30
N	Typical 2.54
P	2.40±0.40
Q	9.20±0.40
S	0.25±0.15
T	0.25±0.15
U	2.80±0.30
DIA	寬 1.50±0.10 深 0.50 MAX

